12500 TI Boulevard, MS 8640, Dallas, Texas 75243

# PCN#20250602001.1
# Qualification of an alternate Mount Compound material for select devices
# Change Notification / Sample Request

**Date:** June 02, 2025
**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

**20250602001.1**
**Change Notification / Sample Request**
**Attachments**

## Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

| DEVICE | CUSTOMER PART NUMBER |
|---|---|
| TPS61322DBZR | TPS61322DBZR |
| TMUX1219DCKR | TMUX1219DCKR |

Technical details of this Product Change follow on the next page(s).

| PCN Number: | 20250602001.1 | PCN Date: | June 02, 2025 |
|---|---|---|---|
| Title: | Qualification of an alternate mount compound material for select devices | | |
| Customer Contact: | Change Management team | Dept: | Quality Services |
| Proposed 1st Ship Date: | August 31, 2025 | Sample Requests accepted until: | August 01, 2025* |

***Sample requests received after August 01, 2025 will not be supported.**

**Change Type:**

| | | | | | |
|---|---|---|---|---|---|
| ☐ | Assembly Site | ☐ | Design | ☐ | Wafer Bump Material |
| ☐ | Assembly Process | ☐ | Data Sheet | ☐ | Wafer Bump Process |
| ☒ | Assembly Materials | ☐ | Part number change | ☐ | Wafer Fab Site |
| ☐ | Mechanical Specification | ☐ | Test Site | ☐ | Wafer Fab Material |
| ☐ | Packing/Shipping/Labeling | ☐ | Test Process | ☐ | Wafer Fab Process |

## PCN Details

**Description of Change:**

This PCN is to inform of an alternate Mount Compound material set for the list of devices in the product affected sections below.

**Group 1 Device:**

| What | Current | Additional |
|---|---|---|
| Mount Compound | SID#A-09 | 4229877 |

**Group 2 Device:**

| What | Current | Additional |
|---|---|---|
| Mount Compound | SID#A-09 | 4226215, 4229877 |

Qualification results are shown below

**Reason for Change:**

Standardization

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

None

**Impact on Environmental Ratings**

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

| RoHS | REACH | Green Status | IEC 62474 |
|---|---|---|---|
| ☒ No Change | ☒ No Change | ☒ No Change | ☒ No Change |

**Changes to product identification resulting from this PCN:**

None

**Group 1 Product Affected:**

| | | |
|---|---|---|
| TMUX1119DCKR | TMUX1219DCKR | TMUX1247DCKR |

**Group 2 Product Affected:**

| | |
|---|---|
| TPS61322DBZR | TPS61322DBZT |

# Group 1 Qualification Report

Approve Date 01-May-2025

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | # | Test Name | Condition | Duration | Qual Device: TMUX1119DCKR | Qual Device: TMUX1247DCKR | Qual Device: TMUX1219DCKR | QBS Reference: LM74700QDBVRQ1 | QBS Reference: ESD2CANFD36DCKRQ1 | QBS Reference: UCC287502DBVR | QBS Reference: ESD2CAN24DCKRQ1 |
|---|---|---|---|---|---|---|---|---|---|---|---|
| HAST | A2 | Biased HAST | 130C/85%RH | 96 Hours | - | - | - | 3/231/0 | 2/154/0 | - | 1/77/0 |
| UHAST | A3 | Autoclave | 121C/15psig | 96 Hours | - | - | - | - | - | 3/231/0 | - |
| UHAST | A3 | Unbiased HAST | 130C/85%RH | 96 Hours | - | - | - | 3/231/0 | 1/77/0 | - | 2/154/0 |
| TC | A4 | Temperature Cycle | -65C/150C | 500 Cycles | 1/77/0 | 1/77/0 | 1/77/0 | 3/231/0 | 1/77/0 | 3/231/0 | 2/154/0 |
| HTSL | A6 | High Temperature Storage Life | 150C | 1000 Hours | - | - | - | 3/135/0 | - | - | - |
| SD | C3 | PB-Free Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes) | - | - | - | - | 1/15/0 | - | - | 1/15/0 |
| PD | C4 | Physical Dimensions | Cpk>1.67 | - | 1/30/0 | 1/30/0 | 1/30/0 | 3/30/0 | 1/30/0 | - | 1/30/0 |
| FTY | E6 | Final Test Yield | - | - | - | Pass | - | - | - | - | - |

QBS: Qual By Similarity, also known as Generic Data
Qual Device TMUX1119DCKR is qualified at MSL1 260C
Qual Device TMUX1247DCKR is qualified at MSL1 260C
Qual Device TMUX1219DCKR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2402-021

# Group 2 Qualification Report

Approve Date 02-May-2024

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | # | Test Name | Condition | Duration | Qual Device: UCC287502DBVR | QBS Reference: TPS3808EG01DBVRQ1 | QBS Reference: LM74700QDBVRQ1 | QBS Reference: PUCC287502DBVR |
|---|---|---|---|---|---|---|---|---|
| UHAST | A3 | Autoclave | 121C/15psig | 96 Hours | 3/231/0 | - | - | - |
| UHAST | A3 | Unbiased HAST | 130C/85%RH | 96 Hours | - | 1/77/0 | 3/231/0 | - |
| TC | A4 | Temperature Cycle | -65C/150C | 500 Cycles | 3/231/0 | 1/77/0 | 3/231/0 | - |
| HTSL | A6 | High Temperature Storage Life | 150C | 1000 Hours | - | 1/45/0 | 3/135/0 | - |
| HTOL | B1 | Life Test | 150C | 300 Hours | - | - | 1/77/0 | - |
| SD | C3 | PB Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes) | - | - | - | 1/15/0 | - |
| SD | C3 | PB-Free Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes) | - | - | - | 1/15/0 | - |
| PD | C4 | Physical Dimensions | Cpk>1.67 | - | - | 1/10/0 | 3/30/0 | - |
| ESD | E2 | ESD CDM | - | 250 Volts | - | - | - | 1/3/0 |
| ESD | E2 | ESD CDM | - | 500 Volts | - | 1/3/0 | - | - |
| ESD | E2 | ESD HBM | - | 1000 Volts | - | - | - | 1/3/0 |
| ESD | E2 | ESD HBM | - | 2000 Volts | - | 1/3/0 | - | - |
| LU | E4 | Latch-Up | Per JESD78 | - | - | 1/6/0 | - | 1/3/0 |
| CHAR | E5 | Electrical Characterization | Per Datasheet Parameters | - | 1/30/0 | - | - | 1/30/0 |
| CHAR | E5 | Electrical Distributions | Cpk>1.67 Room, hot, and cold | - | - | 1/30/0 | 1/30/0 | - |

QBS: Qual By Similarity
Qual Device UCC287502DBVR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2312-020

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS

Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

**IMPORTANT NOTICE AND DISCLAIMER**